Winstar Display Co., LTD 華凌光電股份有限公司



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SPECIFICATION

CUSTOMI	ER :						
MODULE NO.:		WG320240E-TFI-NZ#					
APPROVE	ED BY:						
(FOR CUSTOMER USE ONLY)		РСВ ч	VERSION:	DATA:			
SALES BY	APPROVED	BY	CHECKED BY	PREPARED BY			

VERSION	DATE	REVISED PAGE NO.	SUMMARY
	2011/02/12		First issue



MODLE NO:

RECO	ORDS OF REVI	DOC. FIRST ISSUE	
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1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type

3 Display Font: 320 * 240 Dots

Model serials number

 \bigcirc Backlight Type : N \rightarrow Without backlight A \rightarrow LED, Amber

 $B\rightarrow EL$, Blue green $R\rightarrow LED$, Red

D→EL, Green O→LED, Orange

 $W\rightarrow EL$, White $G\rightarrow LED$, Green

 $F\rightarrow CCFL$, White $T\rightarrow LED$, White

Y→LED, Yellow Green

© LCD Mode : $B \rightarrow TN$ Positive, Gray $T \rightarrow FSTN$ Negative

N→TN Negative,

G→STN Positive, Gray

Y→STN Positive, Yellow Green

M→STN Negative, Blue

F→FSTN Positive

⑦ LCD Polarize Type/ A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Temperature range/ D→Reflective, N.T, 12:00 K→Transflective, W.T, 12:00 View direction

G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00

J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00

E→Transflective, N.T.12:00 L→Transmissive,

W.T,12:00

Special Code
N:Without Build in Negative Voltage;

Z: IC NT7086;

#:Fit in with the ROHS Directions and regulations

2. Precautions in Use of LCD Module

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD Module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components
- (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev.

3. General Specification

ITEM	STANDARD VALUE	UNIT			
Number of dots	320x240	dots			
Outline dimension	143.0(W)x 96.8(H)x 12.6max(T)	mm			
View area	104.0(W)x 79.3(H)	mm			
Active area	95.98(W)x 71.98(H)	mm			
Dot size	0.28(W)x 0.28(H)	mm			
Dot pitch	0.3(W)x 0.3(H)	mm			
LCD type	FSTN Positive Transmiss (In LCD production, It will occur slightly color guarantee the same color in the same batch.)	,			
View direction	6 o'clock				
Duty Method	1/240 Duty				
Backlight	LED, White				

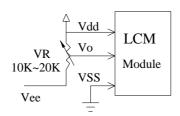
4. Absolute Maximum Ratings

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT
Operating Temperature	T_{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	$V_{\rm I}$	0	_	5	V
Supply Voltage For Logic	V_{DD}	0	_	6.5	V
Supply Voltage For LCD	V_{DD} - V_{EE}	0	_	22.4	V

5. Electrical Characteristics

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Logic Voltage	V_{DD} - V_{SS}	$V_{DD} = 3V,5V$	2.7		5.5	V
Supply Voltage For		Ta=-20°C	=	_	_	V
LCD	V_{DD} - V_{O}	Ta=25°C	23.5	24.2	24.9	V
*Note		Ta=+70°C	_	_	_	V
Input High Volt.	V_{IH}	_	$0.8V_{DD}$	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	-0.3	_	$0.2V_{DD}$	V
Output High Volt.	V_{OH}	_	V _{DD} -0.4	_	V_{DD}	V
Output Low Volt.	V_{OL}	_	0	_	0.4	V
Supply Current	I_{DD}	V=5.0V	30	45	50	mA

^{*} Note: Please design the VOP adjustment circuit on customer's main board



6. Optical Characteristics

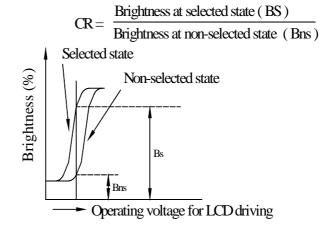
ITEM	SYMBAL	CONDITION	MIN	TYP	MAX	UNIT
View Angle	$(V)\theta$	CR≧3	30	_	60	deg.
	(H) φ	CR≧3	-45	_	45	deg.
Contrast Ratio	CR	_	_	5	_	_
Response Time	T rise	_	_	200	300	ms
	T fall	_		150	200	ms

6.1 Definitions

■View Angles

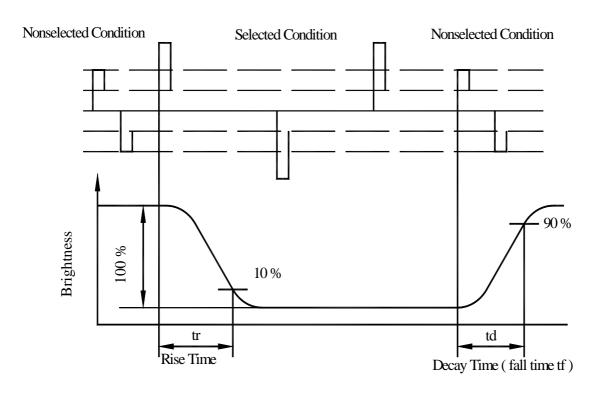
Z (Visual angle direction) X_{ϕ}

Contrast Ratio



Response time

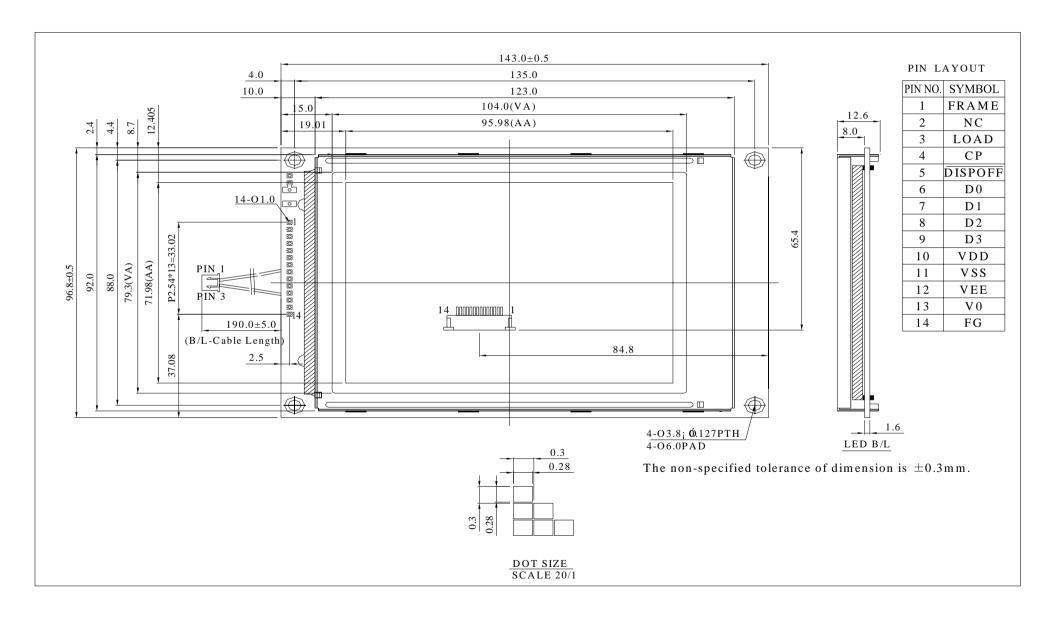
 Y_{θ}

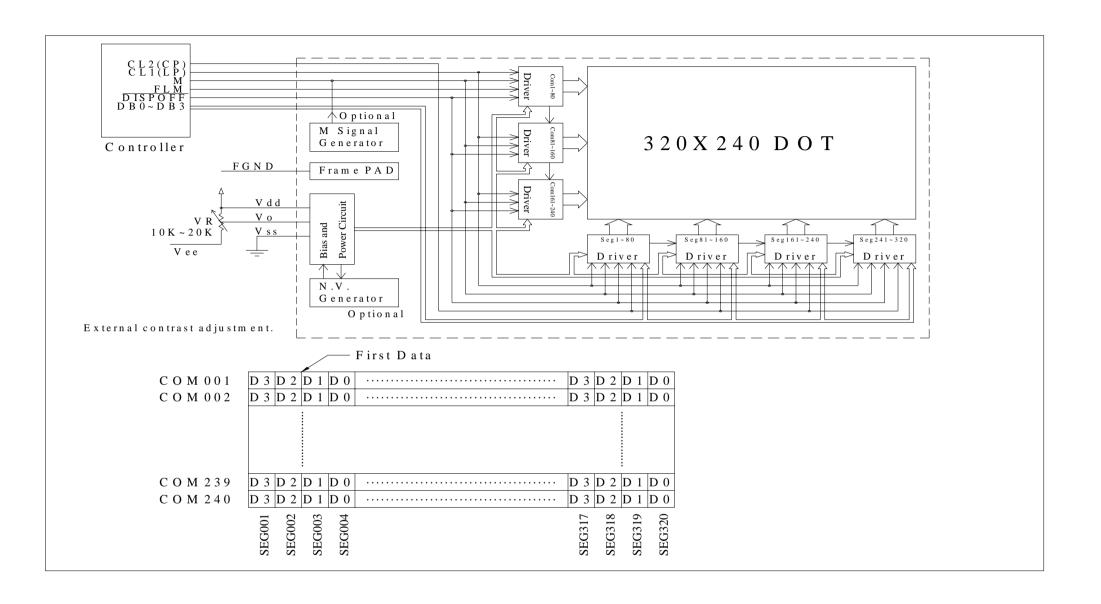


7. Interface Description

Pin No.	Symbol	Level	Description
1	FRAME	H/L	Scan start-up signal
2	NC	H/L	NO connection
3	LOAD(CL1)	H to L	Data latch pulse
4	CP(CL2)	H to L	Data shift pulse
5	DISPOFF	H/L	H: Display ON, L: Display OFF
6	D0	H/L	Data bus line
7	D1	H/L	Data bus line
8	D2	H/L	Data bus line
9	D3	H/L	Data bus line
10	V_{DD}	5.0V	Power supply for Logic
11	V_{SS}	0V	Ground
12	V_{EE}		NC
13	Vo	(Variable)	Driving voltage for LCD
14	FG		Frame Ground

8. Contour Drawing & Block diagram





9. Timing Characteristics

9.1.Common & Segment interface timing:

ITEM	symbol	Test Condition	Min.	Тур.	Max.	Units
Clock Cycle	tC	Fig.1	100	_		ns
CP Pulse Width	tWC	Fig.1	50			ns
LP Pulse Width	tWL	Fig.1	50			ns
Data Set Up Time	tDSU	Fig.1	30	_		ns
Data Hold Time	tDHD	Fig.1	30	_		ns
CP Rise/Fall Time	tr,tf	Fig.1	_	_	50	ns
CP to LOAD	tCL	Fig.1	80	_	_	ns
LOAD to CP	tLC	Fig.1	110	_	_	ns
LP Pulse Width	tLW	Fig.1	50	_	_	ns
CL1 Pulse Width	tCW	Fig.2	63			ns
Data Set Up Time	tDSU2	Fig.2	100	_	_	ns
Data Hold Time	tDHD2	Fig.2	100	_		ns
CL1 Rise/Fall Time	tr2,tf2	Fig.2			50	ns

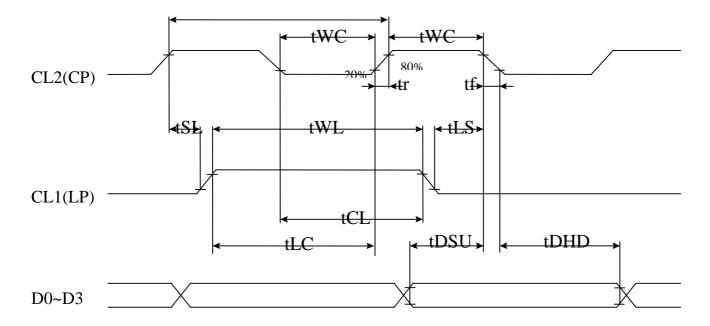


Fig 1. SEGMENT TIMING

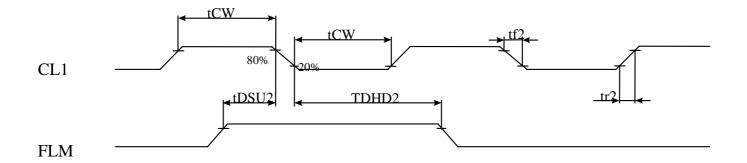
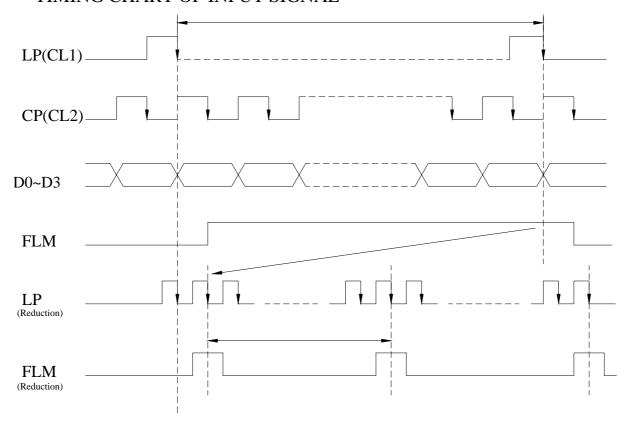
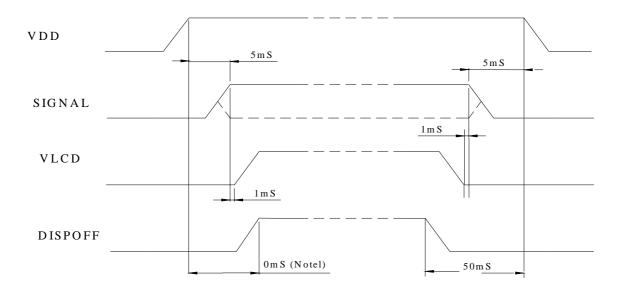


Fig 2 COMMON TIMING

TIMING CHART OF INPUT SIGNAL



POWER ON/OFF TIMING



*Note1: The delay time of /Dispoff signal can be 0ms within VDD input. Owing to having good display quality, /Dispoff signal have to delay at least 10ms or more for waiting power in stable.

10.RELIABILITY

Content of Reliability Test (wide temperature, -20°C~70°C)

Environmental Test									
Test Item	Content of Test	Test Condition	Note						
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2						
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2						
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs							
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1						
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C ,90%RH 96hrs	1,2						
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation $\begin{array}{c ccccccccccccccccccccccccccccccccccc$	-20°C/70°C 10 cycles							
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3						
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time							

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

11. Backlight Information

LED(Edge) backlight Specification

(Ta=25°C)

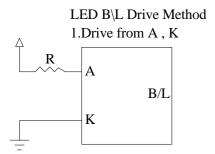
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	115.2	128	200	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	_
Reverse Voltage	VR	_	_	5	V	_
Luminous Intensity	IV	267.7	334.7	_	CD/M ²	ILED=128mA
LED Life Time (For Reference only)	_	_	50K	_	Hr.	ILED=128mA 25℃,50-60%RH, (Note 1)
Color	White	1	1		l	1

Note: The LED of B/L is drive by current only, drive voltage is for reference only.

drive voltage can make driving current under safety area (current between

minimum and maximum).

Note 1:50K hours is only an estimate for reference.



12. Inspection specification

NO	Item		Criterion		AQL		
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 					
02	Black or white spots on LCD (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 					
03	LCD black spots, white spots, contaminati on (non-display	3.1 Round type : As follow $\Phi = (x + y)/2$ $X \qquad Y$ $X \qquad Y$ 3.2 Line type : (As following Length Len	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$		2.5		
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5		

NO	Item	Criterion		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination		
		Symbols Define: x: Chip length y: Chip width z: Chip length t: Glass thickness a: Long L: Electrode pad length: 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between		
06	Chipped glass	z: Chip thickness y: Chip width $ Z \le 1/2t \qquad \text{Not over viewing area} \\ 1/2t < z \le 2t \qquad \text{Not exceed } 1/3k $		2.5
		OIf there are 2 or more chips, x is total length of 6.1.2 Corner crack: $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	f each chip. $x: Chip length$ $x \le 1/8a$ $x \le 1/8a$	
			x ≤ 1/8a	

Item	Criterion				
	Symbols:				
	x: Chip length y: Chip width	z: Chip thickness			
	k: Seal width t: Glass thickness	a: LCD side length			
	L: Electrode pad length				
	6.2 Protrusion over terminal:				
	6.2.1 Chip on electrode pad :				
		Z			
	y: Chip width x: Chip lengt	h z: Chip thickness			
Glass	$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a}$	$0 < z \le t$			
	6.2.2 Non-conductive portion:				
cra	L	· ·	2.5		
ck	A DAY				
	y Z	y Z			
	X	X			
	y: Chip width x: Chip l	ength z: Chip thickness			
	$y \le L$ $x \le 1/2$	$0 < z \le t$			
	⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must				
	remain and be inspected according to electrode terminal specifications.				
	⊙ If the product will be heat sealed by the customer, the alignment mark				
	not be damaged.				
	6.2.3 Substrate protuberance and internal crack.				
	y: v	width x: length			
	y≦	$\frac{1}{3}$ L $x \le a$			
	Glass	Symbols: x: Chip length k: Seal width t: Glass thickness L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad: y: Chip width x: Chip length y≤0.5mm x≤1/8a 6.2.2 Non-conductive portion: cra ck y: Chip width x: Chip length x≤1/8a 6.2.2 Non-conductive portion: I y: Chip width x: Chip length x≤1/8a y: Chip width x: Chip length y≤L x≤1/ oIf the chipped area touches the ITH remain and be inspected according oIf the product will be heat sealed to not be damaged. 6.2.3 Substrate protuberance and internal crafts y: y	$ \begin{array}{c} \text{Symbols:} \\ \text{x: Chip length} \qquad \text{y: Chip width} \qquad \text{z: Chip thickness} \\ \text{k: Seal width} \qquad \text{t: Glass thickness} \qquad \text{a: LCD side length} \\ \text{L: Electrode pad length} \\ \text{6.2 Protrusion over terminal:} \\ \text{6.2.1 Chip on electrode pad:} \\ \\ \hline y: \text{Chip width} \qquad \text{x: Chip length} \qquad \text{z: Chip thickness} \\ \hline y \leq 0.5 \text{mm} \qquad \text{x} \leq 1/8 \text{a} \qquad 0 < z \leq \text{t} \\ \hline \text{6.2.2 Non-conductive portion:} \\ \hline \text{cra} \\ \text{ck} \\ \hline \\ y: \text{Chip width} \qquad \text{x: Chip length} \qquad \text{z: Chip thickness} \\ \hline y \leq L \qquad \text{x} \leq 1/8 \text{a} \qquad 0 < z \leq \text{t} \\ \hline \text{Of the chipped area touches the ITO terminal, over $2/3$ of the ITO must remain and be inspected according to electrode terminal specifications.} \\ \hline \text{Of the product will be heat sealed by the customer, the alignment mark not be damaged.} \\ \hline \text{6.2.3 Substrate protuberance and internal crack.} \\ \hline \text{y: width} \qquad \text{x: length} \\ \hline \end{array} $		

NO	Item	Criterion	AQL
07	Cracked glass The LCD with extensive crack is not acceptable.		2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel 9.1 Bezel may not have rust, be deformed or have fingerprints, stain or other contamination. 9.2 Bezel must comply with job specifications.		2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	2.5 2.5 0.65 2.5 2.5 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin	2.5
		must be present or look as if it cause the interface pin to sever.	
12	General	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12	appearance	component) is not burned into brown or black color.	
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	

13. Material List of Components for RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

•		

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited	100	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm

Above limited value is set up according to RoHS.

2. Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250° C, 30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. $: 235\pm5^{\circ}\mathbb{C}$;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

Recommendable storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module

	winstar LCM Sam	<u>ple Estima</u>	te Feedback Sheet
	nnel Specification		Page: 1
1.	Panel Type:	Pass	□ NG ,
2.	View Direction:	☐ Pass	□ NG ,
3.	Numbers of Dots:	Pass	□ NG ,
4.	View Area:	☐ Pass	□ NG ,
5.	Active Area:	Pass	□ NG ,
6.	Operating Temperature:	☐ Pass	□ NG ,
7.	Storage Temperature:	☐ Pass	□ NG,
8.	Others:		
2 · <u>M</u>	echanical Specification :		
1.	PCB Size:	Pass	☐ NG ,
2.	Frame Size:	Pass	□ NG ,
3.	Materal of Frame:	Pass	☐ NG ,
4.	Connector Position:	Pass	☐ NG ,
5.	Fix Hole Position:	Pass	☐ NG ,
6.	Backlight Position:	Pass	□ NG ,
7.	Thickness of PCB:	Pass	□ NG ,
8.	Height of Frame to PCB:	Pass	☐ NG ,
9.	Height of Module:	Pass	☐ NG ,
10.	Others:	Pass	□ NG ,
3 \ <u>R</u>	elative Hole Size :		
1.	Pitch of Connector:	Pass	□ NG ,
2.	Hole size of Connector:	Pass	□ NG ,
3.	Mounting Hole size:	Pass	□ NG ,
4.	Mounting Hole Type:	Pass	□ NG ,
5.	Others:	Pass	□ NG ,
4 \ <u>Ba</u>	cklight Specification:		
1.	B/L Type:	Pass	□ NG ,
2.	B/L Color:	Pass	□ NG ,
3.	B/L Driving Voltage (Refere	ence for LED	Type): Pass NG,
4.	B/L Driving Current:	Pass	□ NG ,
5.	Brightness of B/L:	Pass	□ NG ,
6.	B/L Solder Method:	Pass	□ NG ,
7.	Others:	Pass	□ NG ,

>> Go to page 2 <<

Modu	winstar Number :		Page: 2
	Electronic Characteristics of M		G
1.	Input Voltage:	Pass	□ NG ,
2.	Supply Current:	Pass	□ NG ,
3.	Driving Voltage for LCD:	Pass	□ NG ,
4.	Contrast for LCD:	Pass	□ NG ,
5.	B/L Driving Method:	Pass	□ NG ,
6.	Negative Voltage Output:	Pass	□ NG ,
7.	Interface Function:	Pass	□ NG ,
8.	LCD Uniformity:	Pass	□ NG ,
9.	ESD test:	Pass	□ NG ,
10.	Others:	Pass	□ NG ,
6 · <u>\$</u>	Summary :		
	Sales signature: Customer Signature:		Date : / /